

# **Description**

The VSM1608N uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

### **General Features**

V<sub>DS</sub> = 16V,I<sub>D</sub> =8A

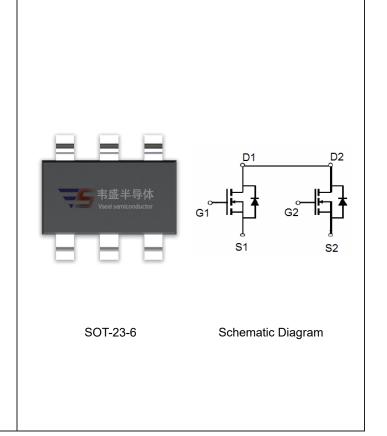
 $R_{DS(ON)}$  < 16m $\Omega$  @  $V_{GS}$ =2.5V

 $R_{DS(ON)}$  < 12m $\Omega$  @  $V_{GS}$ =4.5V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

### **Application**

- Battery protection
- Load switch
- Power management



### **Package Marking and Ordering Information**

	Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
ı	VSM1608N-S6	VSM1608N	SOT-23-6	Ø330mm	12mm	3000 units

## Absolute Maximum Ratings (T<sub>A</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	16	V
Gate-Source Voltage	V <sub>G</sub> s	±12	V
Drain Current-Continuous	I <sub>D</sub>	8	А
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	30	А
Maximum Power Dissipation	P <sub>D</sub>	1.5	W
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	$^{\circ}$

### **Thermal Characteristic**

Thermal Resistance,Junction-to-Ambient (Note 2)	R <sub>θJA</sub>	83.3	°C/W	1
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# Electrical Characteristics (T<sub>A</sub>=25 ℃ unless otherwise noted)

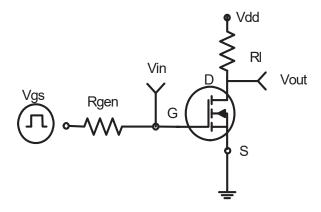
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	20	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ =16 $V$ , $V_{GS}$ =0 $V$	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS}=\pm12V, V_{DS}=0V$	-	-	±100	nA
On Characteristics (Note 3)			•	•		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=250\mu A$	0.5	0.7	1.2	V
Droin Source On State Registance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A	-	10	12	mΩ
Orain-Source On-State Resistance		V <sub>GS</sub> =2.5V, I <sub>D</sub> =5.5A	-	12.9	16	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =6A	-	10	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>lss</sub>	V <sub>DS</sub> =10V,V <sub>GS</sub> =0V, F=1.0MHz	-	1150	-	PF
Output Capacitance	C <sub>oss</sub>		-	185	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F-1.0WI1Z	-	145	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	6	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =10 $V$ , $I_{D}$ =6 $A$	-	13	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =4.5 $V$ , $R_{GEN}$ =6 $\Omega$	-	52	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	16	-	nS
Total Gate Charge	Qg	10111 04	-	15	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =10V, $I_{D}$ =6A, $V_{GS}$ =4.5V	-	0.8	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> -4.5V	-	3.2	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =6A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	8	Α

### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width  $\leq 300 \mu s$ , Duty Cycle  $\leq 2\%$ .
- 4. Guaranteed by design, not subject to production



## **Typical Electrical and Thermal Characteristics**



**Figure 1:Switching Test Circuit** 

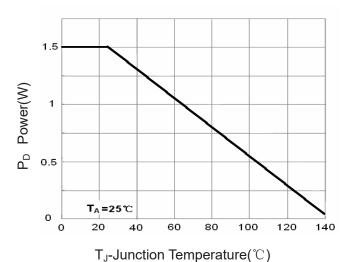
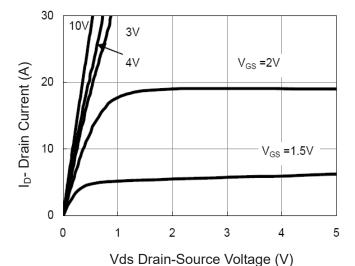


Figure 3 Power Dissipation



**Figure 5 Output Characteristics** 

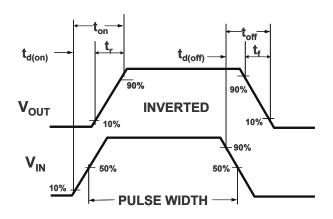
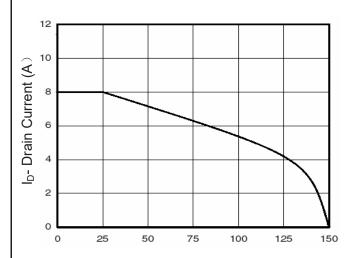
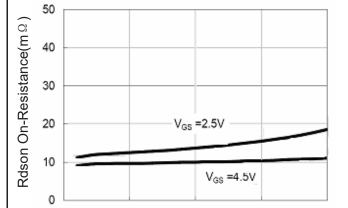


Figure 2:Switching Waveforms



T<sub>J</sub>-Junction Temperature(°C)

Figure 4 Drain Current



I<sub>D</sub>- Drain Current (A)

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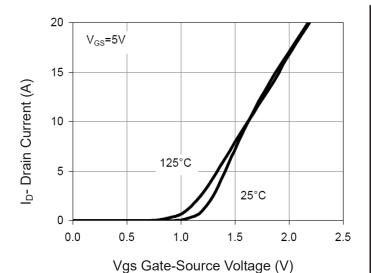
Figure 6 Drain-Source On-Resistance

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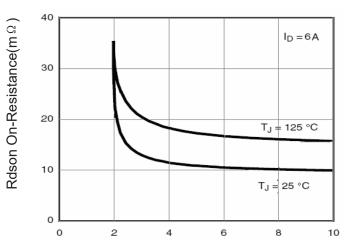
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**Figure 7 Transfer Characteristics** 



Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs

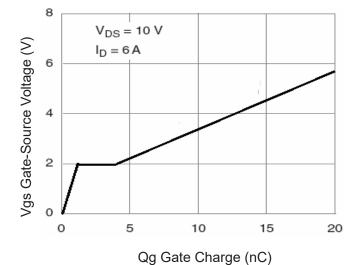


Figure 11 Gate Charge

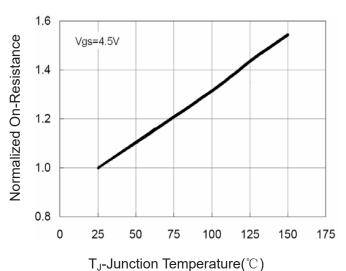


Figure 8 Drain-Source On-Resistance

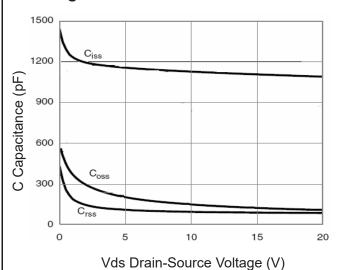
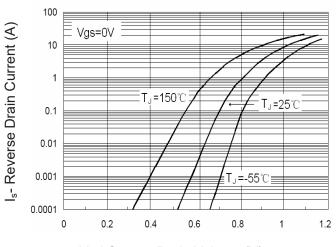


Figure 10 Capacitance vs Vds



Vsd Source-Drain Voltage (V)

Figure 12 Source- Drain Diode Forward



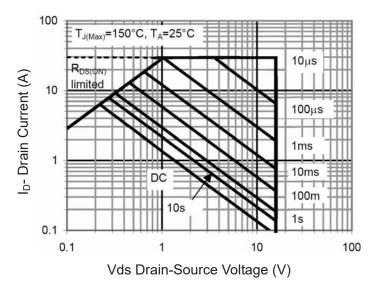
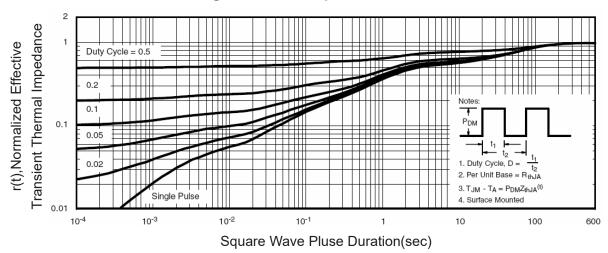


Figure 13 Safe Operation Area



**Figure 14 Normalized Maximum Transient Thermal Impedance**